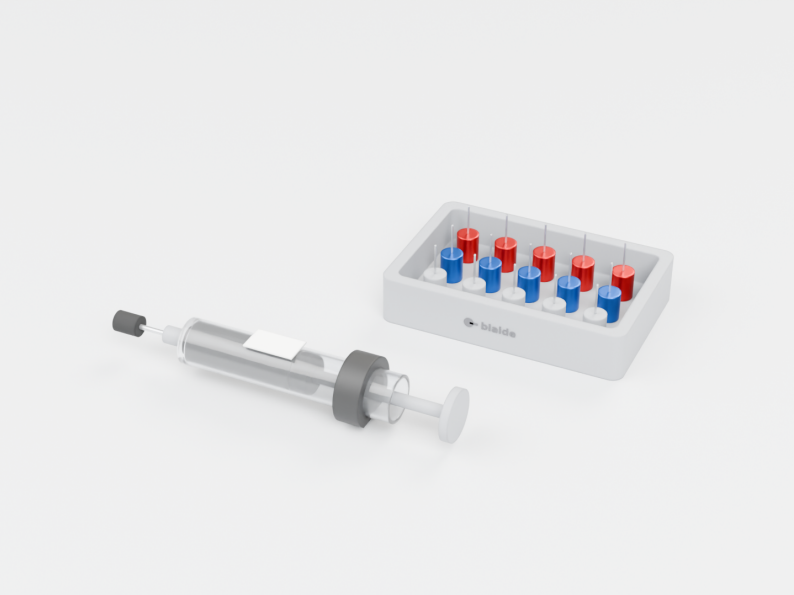
Via kit: Specification

VIA | Blaide product line | 17 November 2026 | Design only: nothing built or tested



Requirements

- Two-sided boards without rivets or wire links
- Vias survive reflow
- User can prove a batch before committing a real board

Specification

Parameter	Target
Via size	0.4 to 1.0 mm drilled, 1.6 mm board
Paste per 0.6 mm via	about 0.5 uL
Estimated resistance	3.33 milliohm per filled 0.6 mm via
Coupon	21 vias in a chain, about 70 milliohm plus traces
Cure	150 C for 30 minutes on the printer bed (planning value)
Nozzle	0.4 mm

Design summary

- Fill from the top over a blotter, cure, flip, top up, cure
- Planner fills holes of 1.0 mm or less with copper on both sides; larger holes are left for part leads
- Coupon: 21 vias in a chain, alternate links on top and bottom, a probe pad at each end

All figures are design targets, calculations or planning values.